

Data sheet acquired from Harris Semiconductor SCHS209

CD74HC4067, CD74HCT4067

High-Speed CMOS Logic 16-Channel Analog Multiplexer/Demultiplexer

February 1998

Features
Wide Analog Input Voltage Range
• Low "ON" Resistance - V _{CC} = 4.5V
Fast Switching and Propagation Speeds
• "Break-Before-Make" Switching 6ns (Typ) at 4.5V
 Available in Both Narrow and Wide-Body Plastic Packages
 Fanout (Over Temperature Range) Standard Outputs
• Wide Operating Temperature Range55°C to 125°C
Balanced Propagation Delay and Transition Times

Significant Power Reduction Compared to LSTTL

- High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC}

- at $V_{CC} = 5V$
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility,
 V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)
 - CMOS Input Compatibility, $I_I \le 1\mu A$ at V_{OL} , V_{OH}

Description

The Harris CD74HC4067 and CD74HCT4067 are digitally controlled analog switches which utilize silicon-gate CMOS technology to achieve operating speeds similar to LSTTL with the low power consumption of standard CMOS integrated circuits.

These analog multiplexers/demultiplexers control analog voltages that may vary across the voltage supply range. They are bidirectional switches thus allowing any analog input to be used as an output and visa-versa. The switches have low "on" resistance and low "off" leakages. In addition, these devices have an enable control which when high will disable all switches to their "off" state.

Ordering Information

	RANGE C) PACKAGE	PKG. NO.
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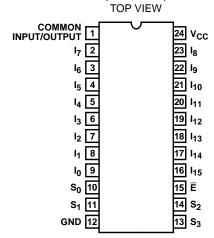
Pinout

Logic ICs

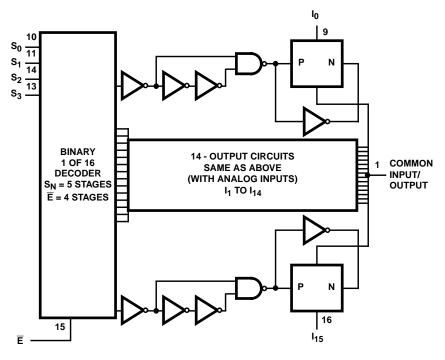
- 2V to 6V Operation

HC Types

CD74HC4067, CD74HCT4067 (PDIP, SOIC)



Functional Diagram



TRUTH TABLE

S0	S 1	S 2	S 3	Ē	SELECTED CHANNEL
Х	Х	Х	Х	1	None
0	0	0	0	0	0
1	0	0	0	0	1
0	1	0	0	0	2
1	1	0	0	0	3
0	0	1	0	0	4
1	0	1	0	0	5
0	1	1	0	0	6
1	1	1	0	0	7
0	0	0	1	0	8
1	0	0	1	0	9
0	1	0	1	0	10
1	1	0	1	0	11
0	0	1	1	0	12
1	0	1	1	0	13
0	1	1	1	0	14
1	1	1	1	0	15

NOTE:

H = High Level

L = Low Level

X = Don't Care

Absolute Maximum Ratings

DC Supply Voltage, V _{CC}
(Voltages Referenced to Ground)0.5V to 7V
DC Input Diode Current, I _{IK}
For $V_1 < -0.5V$ or $V_1 > V_{CC} + 0.5V$
DC Drain Current, I _O
For -0.5V < V _O < V _{CC} + 0.5V
DC Output Diode Current, I _{OK}
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$
DC Output Source or Sink Current per Output Pin, IO
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$
DC V _{CC} or Ground Current, I _{CC}

Thermal Information

Thermal Resistance (Typical, Note 3)	θ_{JA} (oC/W)
PDIP Package	60
SOIC Package	
Maximum Junction Temperature (Hermetic Package or I	Die) 175 ⁰ C
Maximum Junction Temperature (Plastic Package)	150 ^o C
Maximum Storage Temperature Range	65°C to 150°C
Maximum Lead Temperature (Soldering 10s) (SOIC - Lead Tips Only)	300°C

Operating Conditions

Temperature Range, T _A	55 ⁰ C to 125 ⁰ C
HC Types	2V to 6V
HCT Types	
DC Input or Output Voltage, V _I , V _O	0V to V _{CC}
Input Rise and Fall Time	
2V	1000ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE

3. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

DC Electrical Specifications

			TEST CONDITIONS				25°C		O 85°C	-55°C TO 125°C		
PARAMETER	SYMBOL	V _I (V)	V _{IS} (V)	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES												
High Level Input	V _{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
Voltage				4.5	3.15	-	-	3.15	-	3.15	-	٧
				6	4.2	-	-	4.2	-	4.2	-	٧
Low Level Input	V _{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	٧
Voltage				4.5	-	-	1.35	-	1.35	-	1.35	٧
				6	-	-	1.8	-	1.8	-	1.8	V
Maximum "ON"	R _{ON}	V _{CC} or	V _{CC} or	4.5	-	70	160	-	200	-	240	Ω
Resistance I _O = 1mA		GND	GND	6	-	60	140	-	175	-	210	Ω
		V _{CC} to	V _{CC} to	4.5	-	90	180	-	225	-	270	Ω
		GND	GND	6	-	80	160	-	200	-	240	Ω
Maximum "ON"	ΔR _{ON}	-	-	4.5	-	10	-	-	-	-	-	Ω
Resistance Between Any Two Switches				6	-	8.5	-	-	-	-	-	Ω
Switch "Off" Leakage Current 16 Channels	I _{IZ}	E = V _{CC}	V _{CC} or GND	6	-	-	±0.8	-	±8	-	±8	μА
Logic Input Leakage Current	I _I	V _{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	μА
Quiescent Device Current I _O = 0mA	Icc	V _{CC} or GND	-	6	-	-	8	-	80	-	160	μА

DC Electrical Specifications (Continued)

		TE CONDI	ST ITIONS		25°C		-40°C TO 85°C		-55°C TO 125°C			
PARAMETER	SYMBOL	V _I (V)	V _{IS} (V)	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HCT TYPES												
High Level Input Voltage	V _{IH}	-	-	4.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5	-	-	0.8	-	0.8	-	0.8	V
Maximum "ON" Resistance	R _{ON}	V _{CC} or GND	V _{CC} or GND	4.5	-	70	160	-	200	-	240	Ω
I _O = 1mA		V _{CC} to GND	V _{CC} to GND	4.5	-	90	180	-	225	-	270	Ω
Maximum "ON" Resistance Between Any Two Switches	ΔR _{ON}	-	-	4.5	-	10	-	-	-	-	-	Ω
Switch "Off" Leakage Current 16 Channels	I _{IZ}	E = V _{CC}	V _{CC} or GND	6	-	-	±0.8	-	±8	-	±8	μА
Logic Input Leakage Current	II	V _{CC} or GND (Note 5)	-	6	-	-	±0.1	-	±1	-	±1	μА
Quiescent Device Current	Icc	V _{CC} or GND	-	6	-	-	8	-	80	-	160	μА
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI _{CC} (Note 4)	V _{CC} -2.1	-	-	-	100	360	-	450	-	490	μА

NOTES:

- 4. For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.
- 5. Any voltage between $V_{\mbox{\footnotesize{CC}}}$ and GND.

HCT Input Loading Table

INPUT	UNIT LOADS
S ₀ - S ₃	0.5
Ē	0.3

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications table, e.g., $360\mu A$ max at $25^{\circ}C$.

Switching Specifications Input $t_{\text{r}}, \, t_{\text{f}} = 6 \text{ns}$

		TEST	ν _{cc}	25°C			-40°C T	O 85°C	-55°C TO 125°C		
PARAMETER	SYMBOL	CONDITIONS	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES	-										
Propagation Delay Time	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	75	-	95	-	110	ns
Switch In to Out			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
		C _L = 15pF	5	-	6	-	-	-	-	-	ns
Switch Turn On	t _{PZH} , t _{PZL}	C _L = 50pF	2	-	-	275	-	345	-	415	ns
E to Out			4.5	-	-	55	-	69	-	83	ns
			6	-	-	47	-	59	-	71	ns
		C _L = 15pF	5	-	23	-	-	-	-	-	ns

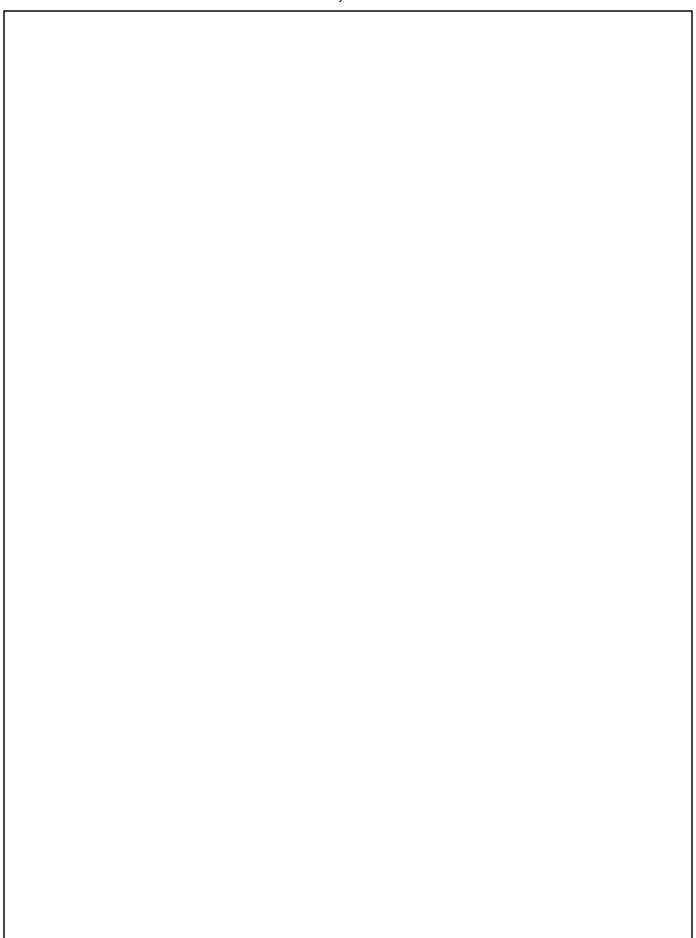
Switching Specifications Input t_r , $t_f = 6ns$ (Continued)

		TEST	v _{cc}		25°C		-40°C 1	O 85°C	-55°C T	O 125°C	
PARAMETER	SYMBOL	CONDITIONS	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Switch Turn On	t _{PZH} , t _{PZL}	C _L = 50pF	2	-	-	300	-	375	-	450	ns
Sn to Out			4.5	-	-	60	-	75	-	90	ns
			6	-	-	51	-	64	-	76	ns
		C _L = 15pF	5	-	25	-	-	-	-	-	ns
Switch Turn Off	t _{PHZ} , t _{PLZ}	C _L = 50pF	2	-	-	275	-	345	-	415	ns
E to Out			4.5	-	-	55	-	69	-	83	ns
			6	-	-	47	-	59	-	71	ns
		C _L = 15pF	5	-	23	-	-	-	-	-	ns
Switch Turn Off	t _{PHZ} , t _{PLZ}	C _L = 50pF	2	-	-	290	-	365	-	435	ns
Sn to Out			4.5	-	-	58	-	73	-	87	ns
			6	-	-	49	-	62	-	74	ns
		C _L = 50pF	5	-	21	-	-	-	-	-	ns
Input (Control) Capacitance	C _I	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 6, 7)	C _{PD}	-	5	-	93	-	-	-	-	-	pF
HCT TYPES	•			•	•						
Propagation Delay Time	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	-	15	-	19	-	22	ns
Switch In to Out		C _L = 15pF	5	-	6	-	-	-	-	-	ns
Switch Turn On	t _{PZH} , t _{PZL}	C _L = 50pF	4.5	-	-	60	-	75	-	90	ns
E to Out		C _L = 15pF	5	-	25	-	-	-	-	-	ns
Switch Turn On	t _{PZH} , t _{PZL}	C _L = 50pF	4.5	-	-	60	-	75	-	90	ns
Sn to Out		C _L = 15pF	5	-	25	-	-	-	-	-	ns
Switch Turn Off	t _{PHZ} , t _{PLZ}	C _L = 50pF	4.5	-	-	55	-	69	-	83	ns
E to Out		C _L = 15pF	5	-	23	-	-	-	-	-	ns
Switch Turn Off	t _{PHZ} , t _{PLZ}	C _L = 50pF	4.5	-	-	58	-	73	-	87	ns
Sn to Out		C _L = 15pF	5	-	21	-	-	-	-	-	ns
Input (Control) Capacitance	CI	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 6, 7)	C _{PD}	-	5	-	96	-	-	-	-	-	pF

NOTES:

^{6.} $C_{\mbox{PD}}$ is used to determine the dynamic power consumption, per package.

^{7.} $P_D = C_{PD} \, V_{CC}^2 \, f_i + \Sigma \, (C_L + C_S) \, V_{CC}^2 \, f_o$ where f_i = input frequency, f_o = output frequency, C_L = output load capacitance, C_S = switch capacitance, V_{CC} = supply voltage.



Analog Channel Specifications T_A = 25°C

PARAMETER	TEST CONDITIONS	V _{CC} (V)	нс/нст	UNITS
Switch Frequency Response Bandwidth at -3dB (Figure 2)	Figure 4, Notes 8, 9	4.5	89	MHz
Sine Wave Distortion	Figure 5	4.5	0.051	%
Feedthrough Noise E to Switch	Figure 6, Notes 9, 10	4.5	TBE	mV
Feedthrough Noise S to Switch			TBE	mV
Switch "OFF" Signal Feedthrough (Figure 3)	Figure 7	4.5	-75	dB
Switch Input Capacitance, C _S		-	5	pF
Common Capacitance, C _{COM}		-	50	pF

NOTES:

- 8. Adjust input level for 0dBm at output, f = 1MHz.
- 9. V_{IS} is centered at $V_{CC}/2$.
- 10. Adjust input for 0dBm at $V_{\mbox{\scriptsize IS}}$.

Typical Performance Curves

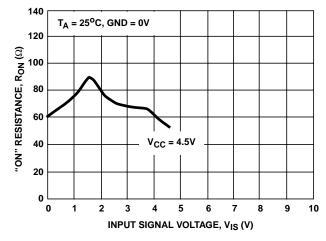


FIGURE 1. TYPICAL "ON" RESISTANCE vs INPUT SIGNAL VOLTAGE

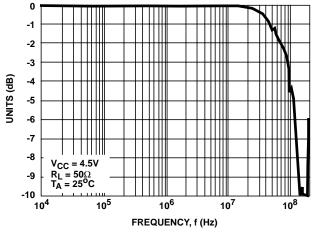


FIGURE 2. TYPICAL SWITCH FREQUENCY RESPONSE

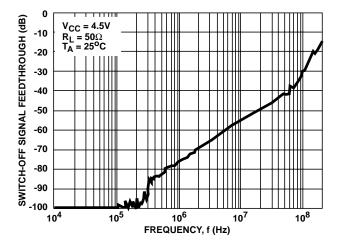


FIGURE 3. TYPICAL SWITCH-OFF SIGNAL FEEDTHROUGH vs FREQUENCY

Analog Test Circuits

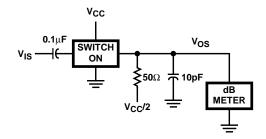


FIGURE 4. FREQUENCY RESPONSE TEST CIRCUIT

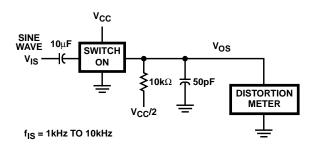


FIGURE 5. SINE WAVE DISTORTION TEST CIRCUIT

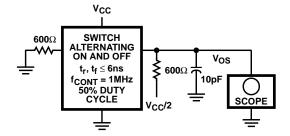


FIGURE 6. CONTROL-TO-SWITCH FEEDTHROUGH NOISE TEST CIRCUIT

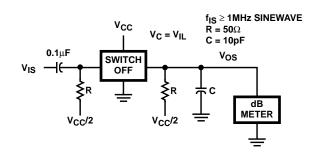


FIGURE 7. SWITCH OFF SIGNAL FEEDTHROUGH TEST CIRCUIT

Test Circuits and Waveforms

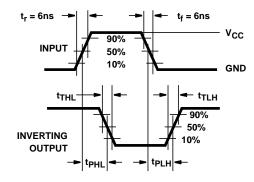


FIGURE 8. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

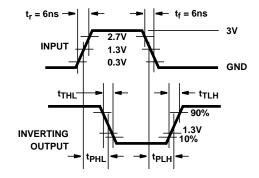


FIGURE 9. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

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